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FORM PTO-1595

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OMB No. 0651-0011 (exp. 4/94)

PATENTS ONLY

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To the Commissioner for Patents:
Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):
William H. Howland

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

3. Nature of conveyance:

- ☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other _____

Execution Date: April 9, 2002

2. Name and address of receiving party(ies)

Name: Solid State Measurements, Inc.

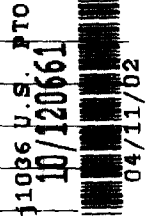
Internal Address: _____

Street Address: 110 Technology Drive

City: Pittsburgh

State: PA ZIP: 15275

Additional name(s) & address(es) attached? ☐ Yes ☒ No



4. Application number(s) or patent number(s):

If this document is being filed together with a new application,
the execution date of the application is: April 9, 2002

A. Patent Application No.(s)

B. Patent No.(s)

Patent application filed concurrently herewith
entitled "Non-Invasive Electrical Measurements Of
Semiconductor Wafers"

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence
concerning document should be mailed:

Name: William H. Logsdon

Internal Address: Webb Ziesenheim Logsdon

Orkin & Hanson, P.C.

Street Address: 700 Koppers Building

436 Seventh Avenue

City: Pittsburgh State: PA ZIP: 15219-1818

6. Total number of applications and
patents involved: 1

7. Total fee (37 CFR 3.41).....\$ 40.00

☒ Enclosed

☐ Authorized to be charged to deposit account

8. Deposit account number:

(Attach triplicate copy of this page if paying by deposit account)

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy
is a true copy of the original document.

Randall A. Notzen, No. 36,882

Name of Person Signing

Randall A. Notzen

Signature

4/11/02

Date

Total number of pages including cover sheet, attachments and document

Mail documents to be recorded with required cover sheet information to:
Commissioner for Patents, U.S. Patent and Trademark Office
Office of Public Records, Crystal Gateway 4, Room 335
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PATENT
REEL: 012796 FRAME: 0095

ASSIGNMENT

WHEREAS, I, William H. Howland, residing at 2535 Secretariat Drive, City of Wexford, County of Allegheny, Commonwealth of Pennsylvania 15090 have invented certain new and useful improvements in "NON-INVASIVE ELECTRICAL MEASUREMENT OF SEMICONDUCTOR WAFERS" for which I have this day executed an application for United States Letters Patent;

AND, WHEREAS, Solid State Measurements, Inc., a corporation of the Commonwealth of Pennsylvania, having a place of business at 110 Technology Drive, Pittsburgh, Pennsylvania 15275, hereinafter called the "assignee", is desirous of acquiring the entire right, title, and interest in and to said application and the inventions and improvements therein disclosed.

NOW, THEREFORE, for good and valuable consideration paid to me by said assignee, the receipt of which is hereby acknowledged, I do hereby assign, sell, transfer, and set over unto said assignee the entire right, title and interest in and to said application and the inventions and improvements therein disclosed for the United States and all foreign countries and any Letters Patent which may issue therefor in the United States and all foreign countries and all divisions, reissues, continuations, continuations-in-part, renewals, and/or extensions thereof, said assignee to have and to hold the interests herein assigned to the full ends of the terms of said Letters Patent and any and all divisions, reissues, continuations, continuations-in-part, renewals, and/or extensions thereof, respectively, as fully and entirely as the same would have been held and enjoyed by me had this assignment not been made.

The Commissioner for Patents is requested to issue such Letters Patent in accordance herewith. I covenant that I am the lawful owner of the said application, inventions, and improvements, that the same are unencumbered, that no license has been granted to make, use, or vend the said inventions or improvements or any of them, and that I have the full right to make this assignment.

And for the consideration aforesaid, I agree that I will communicate to said assignee or the representatives thereof any facts known to me respecting said inventions and improvements, and will, upon request, but without expense to me, testify in any legal proceedings, sign all lawful papers, execute all divisional, reissue, continuation, continuation-in-part, renewal, and/or extension applications, make all rightful oaths, and generally do all other and further lawful acts, deemed necessary or expedient by said assignee or by counsel for said assignee, to assist or enable said assignee to obtain and enforce full benefits from the rights and interests herein assigned. This assignment shall be binding upon my heirs, executors, administrators, and/or assigns, and shall inure to the benefit of the heirs, executors, administrators, successors, and/or assigns, as the case may be, of said assignee.

EXECUTED April 9th, 2002.

William H. Howland
William H. Howland

012041AssnSoleInventor